



## TRISIL™ FOR TELECOM EQUIPMENT PROTECTION

### FEATURES

- Bidirectional crowbar protection
- Voltage range from 8V to 400V
- Low capacitance from 20pF to 45pF @ 50V
- Low leakage current :  $I_R = 2\mu A$  max
- Holding current:  $I_H = 150$  mA min
- Repetitive peak pulse current:  
 $I_{PP} = 100$  A (10/1000 $\mu s$ )

### MAIN APPLICATIONS

Any sensitive equipment requiring protection against lightning strikes and power crossing. These devices are dedicated to central office protection as they comply with the most stressful standards.

Their Low Capacitances make them suitable for ADSL.

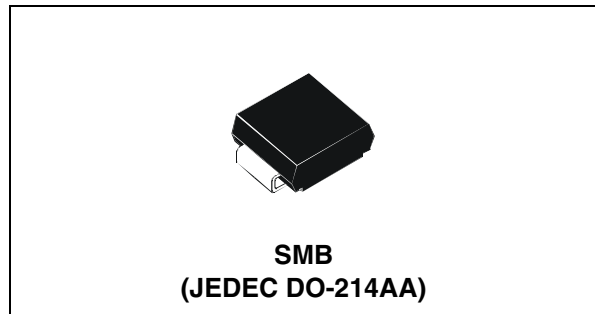
### DESCRIPTION

The SMP100LC is a series of low capacitance transient surge arrestors designed for the protection of high debit rate communication equipment. Its low capacitance avoids any distortion of the signal and is compatible with digital transmission line cards (xDSL, ISDN...).

SMP100LC series tested and confirmed compatible with Cooper Bussmann Telecom Circuit Protector TCP 1.25A.

### BENEFITS

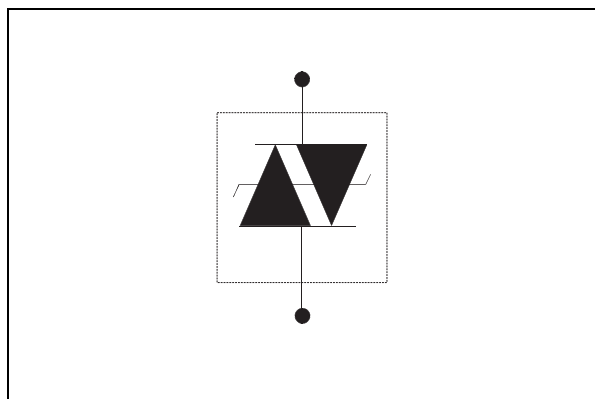
Trisils are not subject to ageing and provide a fail safe mode in short circuit for a better protection. They are used to help equipment to meet main standards such as UL60950, IEC950 / CSA C22.2 and UL1459. They have UL94 V0 approved resin. SMB package is JEDEC registered (DO-214AA). Trisils comply with the following standards GR-1089 Core, ITU-T-K20/K21, VDE0433, VDE0878, IEC61000-4-5 and FCC part 68.



**Table 1: Order Codes**

Part Number	Marking
SMP100LC-8	PL8
SMP100LC-25	L25
SMP100LC-35	L35
SMP100LC-65	L06
SMP100LC-90	L09
SMP100LC-120	L12
SMP100LC-140	L14
SMP100LC-160	L16
SMP100LC-200	L20
SMP100LC-230	L23
SMP100LC-270	L27
SMP100LC-320	L32
SMP100LC-360	L36
SMP100LC-400	L40

**Figure 1: Schematic Diagram**



## SMP100LC

**Table 2: In compliance with the following standards**

STANDARD	Peak Surge Voltage (V)	Waveform Voltage	Required peak current (A)	Current waveform	Minimum serial resistor to meet standard ( $\Omega$ )
GR-1089 Core First level	2500	2/10 $\mu$ s	500	2/10 $\mu$ s	0
	1000	10/1000 $\mu$ s	100	10/1000 $\mu$ s	0
GR-1089 Core Second level	5000	2/10 $\mu$ s	500	2/10 $\mu$ s	0
GR-1089 Core Intra-building	1500	2/10 $\mu$ s	100	2/10 $\mu$ s	0
ITU-T-K20/K21	6000	10/700 $\mu$ s	150	5/310 $\mu$ s	0
	1500		37.5		0
ITU-T-K20 (IEC61000-4-2)	8000	1/60 ns	ESD contact discharge		0
	15000		ESD air discharge		0
VDE0433	4000	10/700 $\mu$ s	100	5/310 $\mu$ s	0
	2000		50		0
VDE0878	4000	1.2/50 $\mu$ s	100	1/20 $\mu$ s	0
	2000		50		0
IEC61000-4-5	4000	10/700 $\mu$ s	100	5/310 $\mu$ s	0
	4000	1.2/50 $\mu$ s	100	8/20 $\mu$ s	0
FCC Part 68, lightning surge type A	1500	10/160 $\mu$ s	200	10/160 $\mu$ s	0
	800	10/560 $\mu$ s	100	10/560 $\mu$ s	0
FCC Part 68, lightning surge type B	1000	9/720 $\mu$ s	25	5/320 $\mu$ s	0

**Table 3: Absolute Ratings ( $T_{amb} = 25^{\circ}\text{C}$ )**

Symbol	Parameter		Value	Unit
$I_{PP}$	Repetitive peak pulse current (see figure 2)	10/1000 $\mu$ s	100	A
		8/20 $\mu$ s	400	
		10/560 $\mu$ s	140	
		5/310 $\mu$ s	150	
		10/160 $\mu$ s	200	
		1/20 $\mu$ s	400	
		2/10 $\mu$ s	500	
$I_{FS}$	Fail-safe mode : maximum current (note 1)	8/20 $\mu$ s	5	kA
$I_{TSM}$	Non repetitive surge peak on-state current (sinusoidal)	t = 0.2 s	24	A
		t = 1 s	15	
		t = 2 s	12	
		t = 15 mn	4	
$I^2t$	$I^2t$ value for fusing	t = 16.6 ms	20	$\text{A}^2\text{s}$
		t = 20 ms	21	
$T_{stg}$	Storage temperature range		-55 to 150	$^{\circ}\text{C}$
$T_j$	Maximum junction temperature		150	$^{\circ}\text{C}$
$T_L$	Maximum lead temperature for soldering during 10 s.		260	$^{\circ}\text{C}$

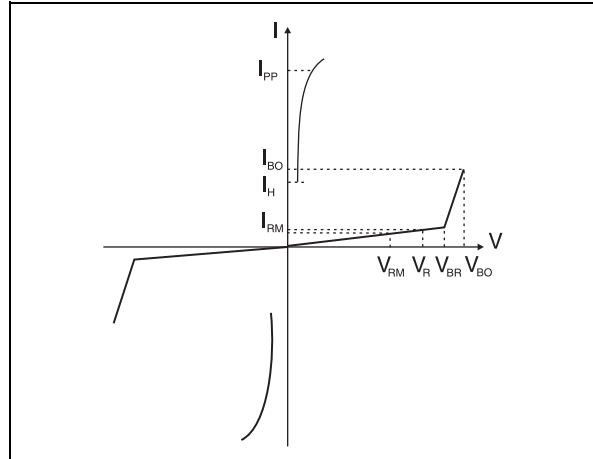
**Note 1:** in fail safe mode, the device acts as a short circuit

**Table 4: Thermal Resistances**

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient (with recommended footprint)	100	°C/W
$R_{th(j-l)}$	Junction to leads	20	°C/W

**Table 5: Electrical Characteristics** ( $T_{amb} = 25^{\circ}C$ )

Symbol	Parameter
$V_{RM}$	Stand-off voltage
$V_{BR}$	Breakdown voltage
$V_{BO}$	Breakover voltage
$I_{RM}$	Leakage current
$I_{PP}$	Peak pulse current
$I_{BO}$	Breakover current
$I_H$	Holding current
$V_R$	Continuous reverse voltage
$I_R$	Leakage current at $V_R$
C	Capacitance



Types	$I_{RM} @ V_{RM}$		$I_R @ V_R$		Dynamic $V_{BO}$	Static $V_{BO} @ I_{BO}$		$I_H$	C	C	
	max.		max.		max.	max.	max.	min.	typ.	typ.	
	$\mu A$	V	$\mu A$	V	V	V	mA	mA	pF	pF	
SMP100LC-8	2	6	5	8	25	15	800	150	50 (typ.)	NA	75
SMP100LC-25		22		25	40	35				NA	65
SMP100LC-35		32		35	55	55				NA	55
SMP100LC-65		55		65	85	85				45	90
SMP100LC-90		81		90	120	125				40	80
SMP100LC-120		108		120	155	160				35	75
SMP100LC-140		120		140	185	190				30	65
SMP100LC-160		144		160	205	200				30	65
SMP100LC-200		180		200	255	250				30	60
SMP100LC-230		207		230	295	285				30	60
SMP100LC-270		243		270	345	335				30	60
SMP100LC-320		290		320	400	390				25	50
SMP100LC-360		325		360	460	450				25	50
SMP100LC-400		360		400	540	530				20	45

**Note 1:**  $I_R$  measured at  $V_R$  guarantee  $V_{BR} \min \geq V_R$

**Note 2:** see functional test circuit 1

**Note 3:** see test circuit 2

**Note 4:** see functional holding current test circuit 3

**Note 5:**  $V_R = 50V$  bias,  $V_{RMS}=1V$ ,  $F=1MHz$

**Note 6:**  $V_R = 2V$  bias,  $V_{RMS}=1V$ ,  $F=1MHz$

Figure 2: Pulse waveform

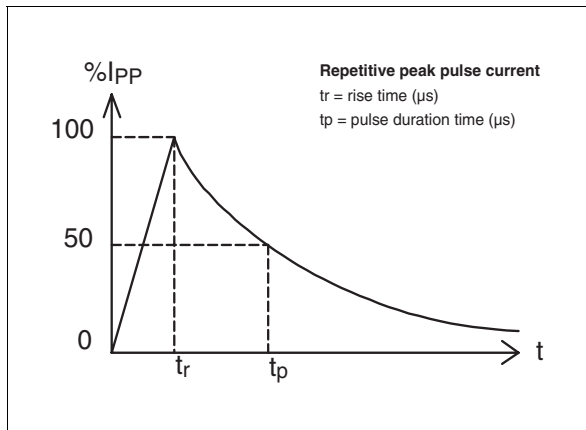


Figure 3: Non repetitive surge peak on-state current versus overload duration

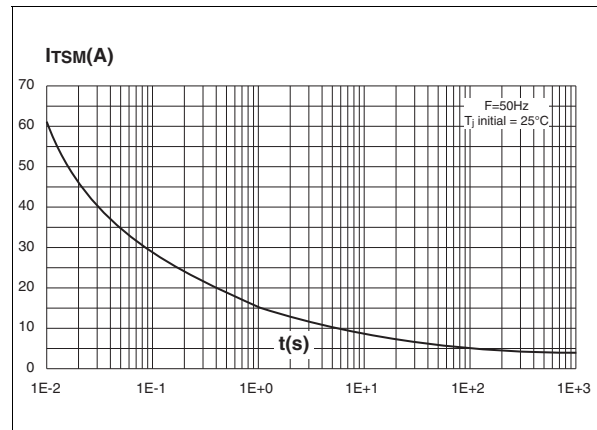


Figure 4: On-state voltage versus on-state current (typical values)

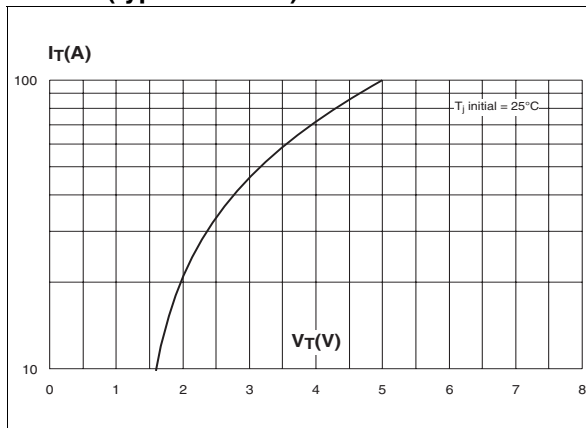


Figure 5: Relative variation of holding current versus junction temperature

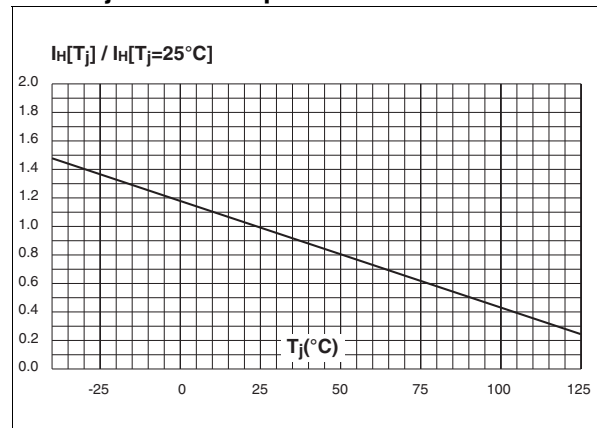


Figure 6: Relative variation of breakover voltage versus junction temperature

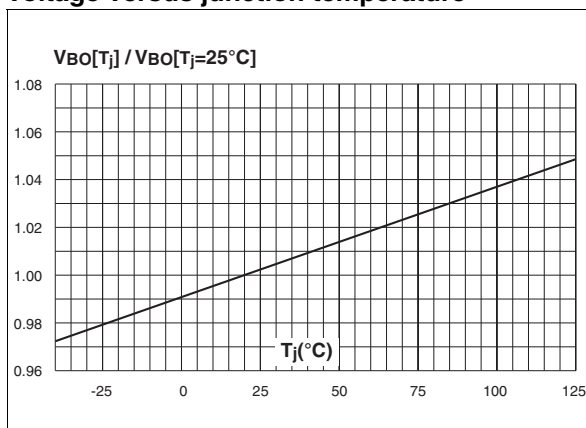
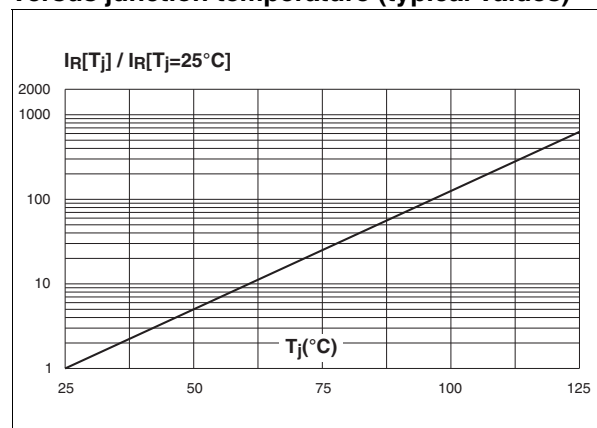
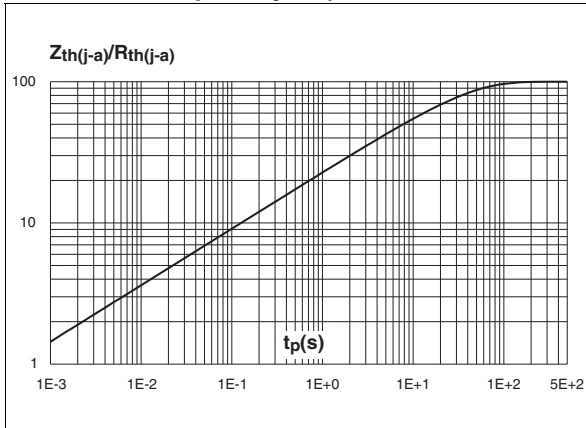


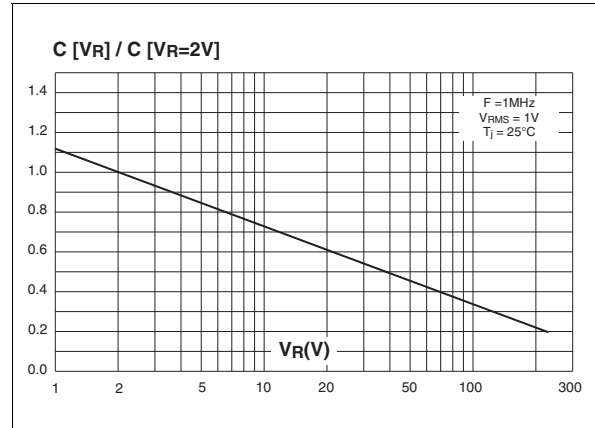
Figure 7: Relative variation of leakage current versus junction temperature (typical values)



**Figure 8: Variation of thermal impedance junction to ambient versus pulse duration (Printed circuit board FR4, SCu=35µm, recommended pad layout)**

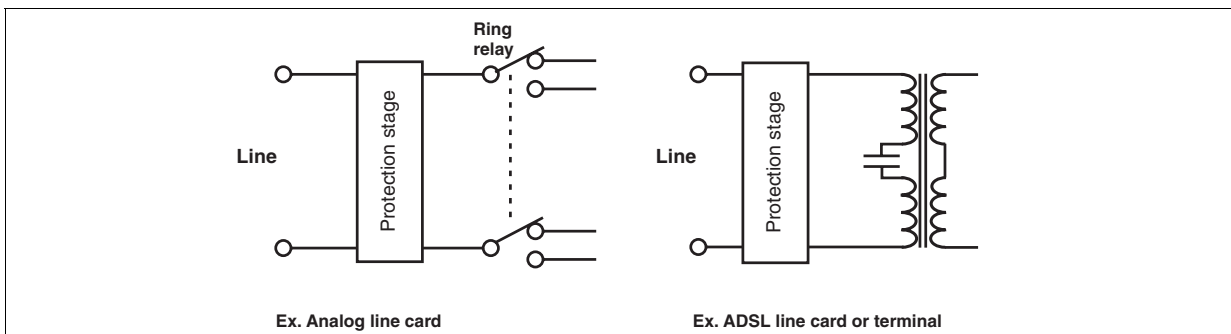


**Figure 9: Relative variation of junction capacitance versus reverse voltage applied (typical values)**

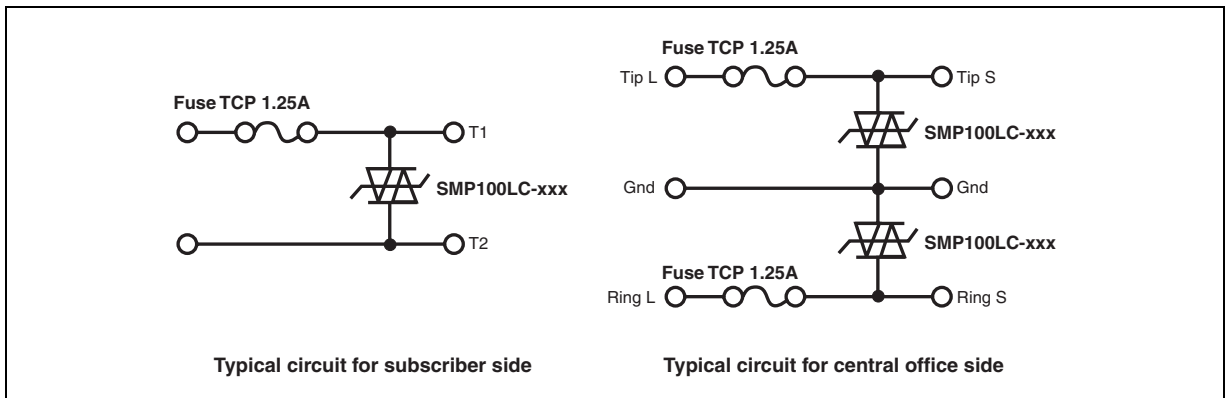


**APPLICATION NOTE**

In wireline applications, analog or digital, both central office and subscriber sides have to be protected. This function is assumed by a combined series / parallel protection stage.

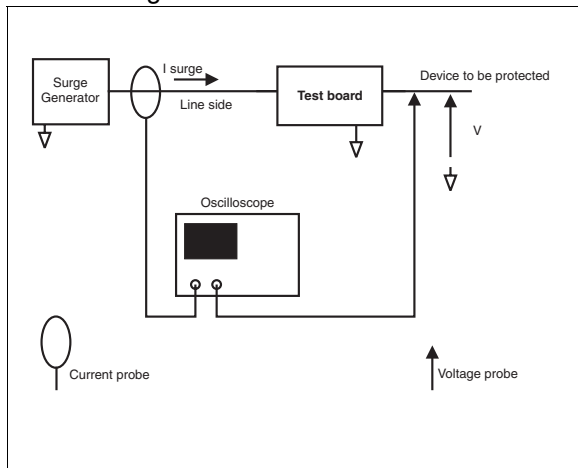


In such a stage, parallel function is assumed by one or several Trisil, and is used to protect against short duration surge (lightning). During this kind of surges the Trisil limits the voltage across the device to be protected at its break over value and then fires. The fuse assumes the series function, and is used to protect the module against long duration or very high current mains disturbances (50/60Hz). It acts by safe circuits opening. Lightning surge and mains disturbance surges are defined by standards like GR1089, FCC part 68, ITU-T K20.

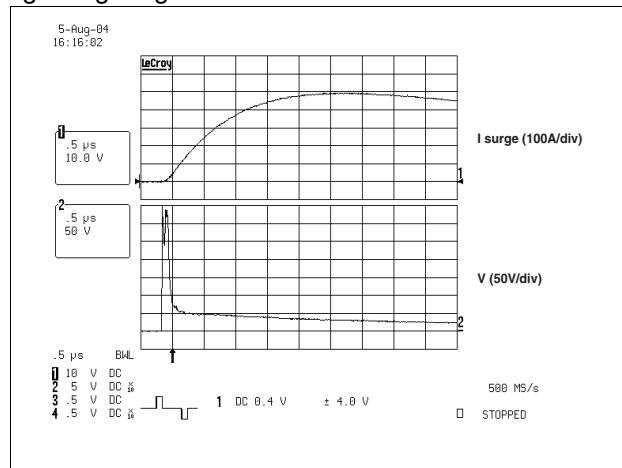


# SMP100LC

Following figure shows the test method of the board having Fuse and Trisil.



Following curve shows the turn on of the Trisil during lightning surge.



These topologies, using SMP100LC from ST and TCP1.25A from Cooper Bussmann, have been functionally validated with a Trisil glued on the PCB. Following example was performed with SMP100LC-270 Trisil. For more information, see Application Note AN2064.

### Test conditions:

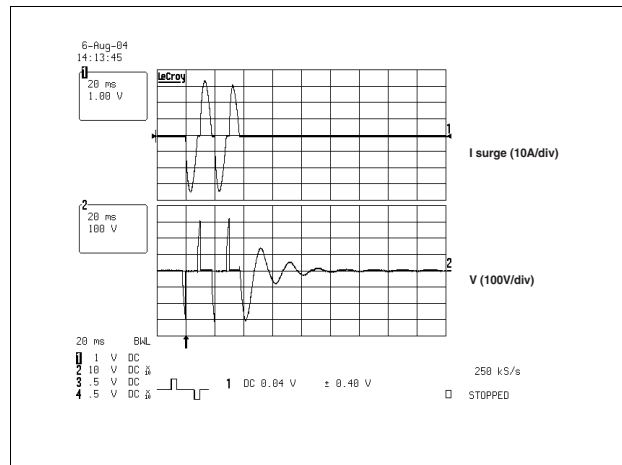
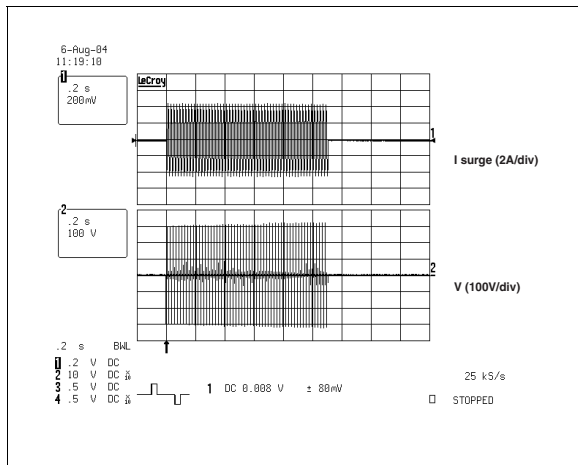
2/10μs + and -2.5 and 5kV 500A (10 pulses of each polarity), T<sub>amb</sub> = 25°C

### Test result:

Fuse and Trisil OK after test in accordance with GR1089 requirements

Following curve shows Trisil action while the fuse remains operational.

In case of high current power cross test, the fuse acts like a switch by opening the circuit.



### Test conditions:

600V 3A 1.1s (first level), T<sub>amb</sub> = 25°C

### Test result:

Fuse and Trisil OK after test in accordance with GR1089 requirements

### Test conditions:

277V 25A (second level), T<sub>amb</sub> = 25°C

### Test result:

Fuse safety opened and Trisil OK after test in accordance with GR1089 requirements

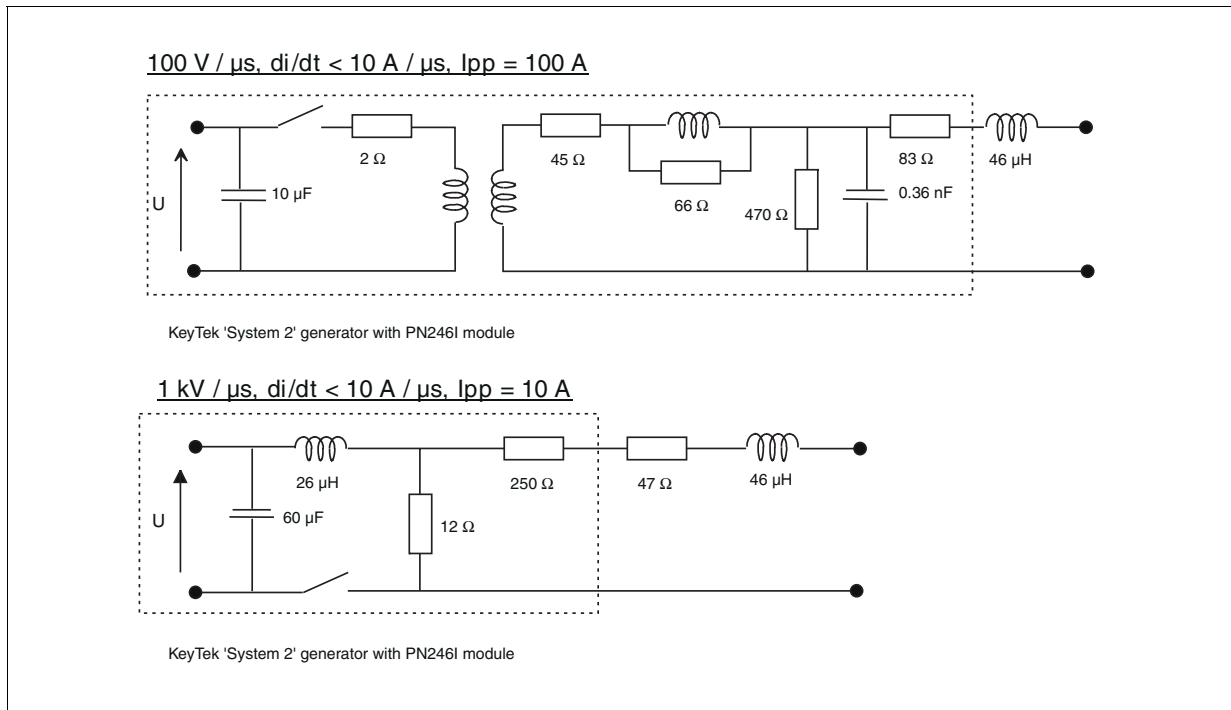
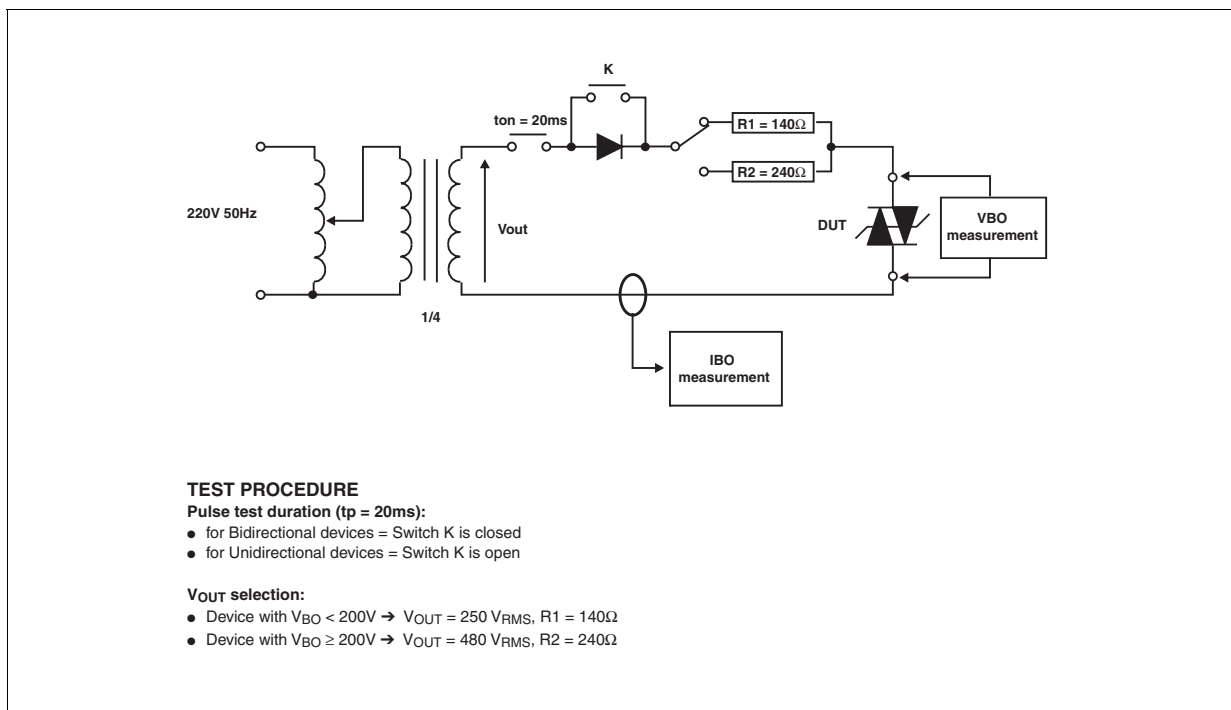
Figure 10: Test circuit 1 for Dynamic  $I_{BO}$  and  $V_{BO}$  parametersFigure 11: Test circuit 2 for  $I_{BO}$  and  $V_{BO}$  parameters

Figure 12: Test circuit 3 for dynamic  $I_H$  parameter

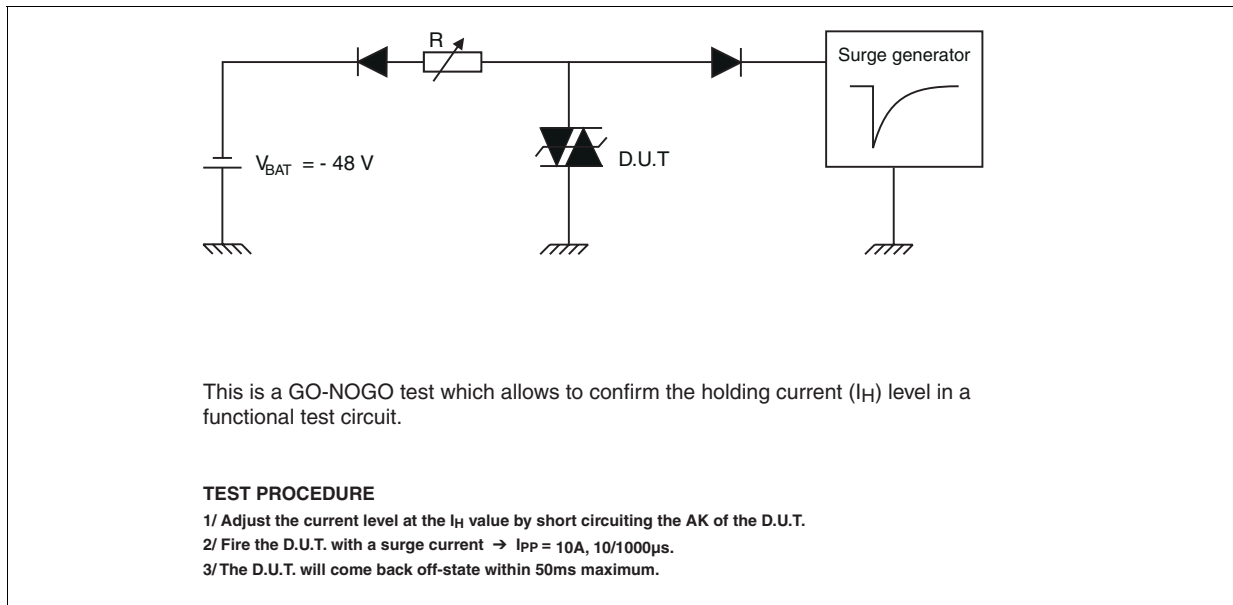


Figure 13: Ordering Information Scheme

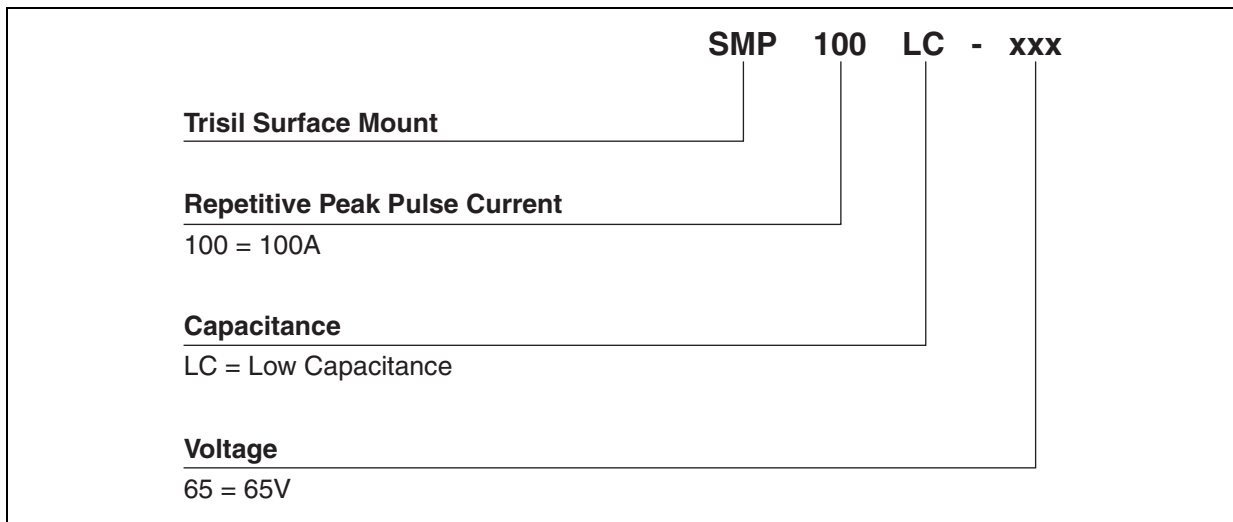




Figure 14: SMB Package Mechanical data

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.41	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.60	0.030	0.063

Figure 15: Foot Print Dimensions (in millimeters)

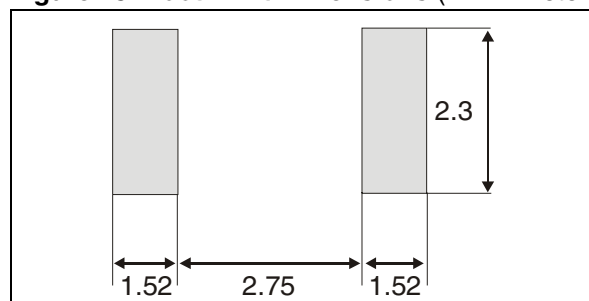


Table 6: Ordering Information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
SMP100LC-8	PL8	SMB	0.11 g	2500	Tape & reel
SMP100LC-25	L25				
SMP100LC-35	L35				
SMP100LC-65	L06				
SMP100LC-90	L09				
SMP100LC-120	L12				
SMP100LC-140	L14				
SMP100LC-160	L16				
SMP100LC-200	L20				
SMP100LC-230	L23				
SMP100LC-270	L27				
SMP100LC-320	L32				
SMP100LC-360	L36				
SMP100LC-400	L40				

Table 7: Revision History

Date	Revision	Description of Changes
09-Nov-2004	9	Absolute ratings values, table 3 on page 2, updated.
07-Dec-2004	10	SMP100LC-320, SMP100LC-360 and SMP100LC-400 addition.
20-Jun-2005	11	Telecom Circuit Protector added

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